

	U	Document ID	Issue Date	Pages	Title
1	<input type="checkbox"/>	US 5612254 A	19970318	15	Methods of forming an interconnect on a semiconductor substrate
2	<input type="checkbox"/>	US 5272117 A	19931221	10	Method for planarizing a layer of material
3	<input type="checkbox"/>	US 4832789 A	19890523	5	Semiconductor devices having multi-level metal interconnects
4	<input type="checkbox"/>	US 4789648 A	19881206	6	Method for producing coplanar multi-level metal/insulator films on a substrate and for forming patterned conductive lines simultaneously

	Current OR	Current XRef	Retrieval Classif	Inventor	S
1	438/634	438/631 ; 438/637 ; 438/672 ; 438/675		Mu, Xiao-Chun , et al.	<input checked="" type="checkbox"/>
2	438/14	216/38 ; 216/52 ; 216/88 ; 438/626 ; 438/692 ; 438/699		Roth, Scott S. , et al.	<input checked="" type="checkbox"/>
3	438/624	257/758 ; 438/637 ; 438/638 ; 438/639		Cochran, William T. , et al.	<input checked="" type="checkbox"/>
4	438/633	216/52 ; 438/634 ; 438/637 ; 438/699		Chow, Melanie M. , et al.	<input checked="" type="checkbox"/>

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